DESCRIPTION

AM4403 is available in a SOP8 package.

FEATURES

-20V/-12.2A,

 $R_{DS(ON)}$ = 14m Ω (max.) @ V_{GS} = -4.5V

 $R_{DS(ON)}$ = 20m Ω (max.) @ V_{GS}= -2.5V

 $R_{DS(ON)}$ = 32m Ω (max.) @ V_{GS} = -1.8V

- Reliable and Rugged
- Available in a SOP8 package.

ORDERING INFORMATION

Package Type	Part Number		
SOD8	MO	AM4403M8R	
SOP8	M8	AM4403M8VR	
Note	V: Halogen free Package		
Note	R: Tape & Reel		
A'T '			

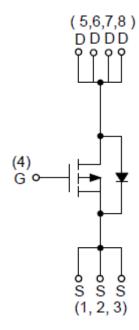
AiT provides all RoHS products

Suffix " V " means Halogen free Package

APPLICATION

Power Management in Notebook Computer,
 Portable Equipment and Battery Powered
 Systems.

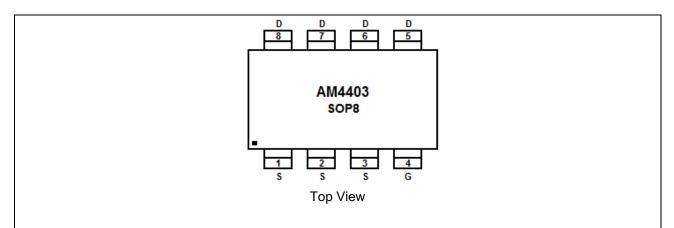
PIN DESCRIPTION



P-Channel MOSFET

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PIN DESCRIPTION



Pin#	Symbol	Function
1	S	Source
2	S	Source
3	S	Source
4	G	Gate
5	D	Drain
6	D	Drain
7	D	Drain
8	D	Drain

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ABSOLUTE MAXIMUM RATINGS

T_A = 25°C, unless otherwise noted

I _A = 25°C, unless otherwise noted			
V _{DSS} , Drain-Source Voltage		-20V	
V _{GSS} , Gate-Source Voltage		±12V	
L NOTE A CONTRACT OF THE CONTR	T _A =25°C	-12.2A	
I _D NOTE1, Continuous Drain Current(V _{GS} =-4.5V)	T _A =70°C	-9.8A	
I _{DM} NOTE1, 300μs Pulsed Drain Current(V _{GS} =-4.5V)		-48.8A	
Is NOTE1, Diode Continuous Forward Current		-3A	
I _{AS} NOTE2, Avalanche Current, Single pulse (L=0.1mH)		-28A	
E _{AS} NOTE2, Avalanche Energy, Single pulse (L=0.1mH)		39mJ	
T _J , Maximum Junction Temperature		150°C	
T _{STG} , Storage Temperature Range		-55°C~150°C	
D. NOTE1 Maximum Dower Dissingtion	T _A =25°C	3.1W	
P _D NOTE1, Maximum Power Dissipation	T _A =70°C	2W	
D NOTE13 The word Decister of Lunction to Ambient	t ≤ 10s	40°C/W	
R _{0JA} NOTE1,3, Thermal Resistance-Junction to Ambient	Steady state	75°C/W	
ReJL, Thermal Resistance-Junction to Lead	Steady state	24°C/W	

Stress beyond above listed "Absolute Maximum Ratings" may lead permanent damage to the device. These are stress ratings only and operations of the device at these or any other conditions beyond those indicated in the operational sections of the specifications are not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

NOTE1: Surface Mounted on $1in^2$ pad area, $t \le 10sec$.

NOTE2: UIS tested and pulse width limited by maximum junction temperature 150°C (initial temperature T_J=25°C).

NOTE3: Maximum under Steady State conditions is 75 $\,^{\circ}\text{C/W}.$

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ELECTRICAL CHARACTERISTICS

 $T_A = 25^{\circ}C$, unless otherwise noted

Parameter	Symbol	Conditions	Min	Тур.	Max	Units
Static Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V,I _{DS} =-250μA	-20	-	-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =-16V,V _{GS} =0V	-	-	-1	μA
		T _J =85°C	ı	ı	-30	
Gate Threshold Voltage	$V_{\text{GS(th)}}$	V _{DS} =V _{GS} ,I _{DS} =-250μA	-0.4	ı	-1	V
Gate Leakage Current	Igss	V _{GS} =±12V, V _{DS} =0V	ı	ı	±100	nA
Drain-Source On-state Resistance	R _{DS(ON)}	V _{GS} =-4.5V,I _{DS} =-12.2A	ı	11	14	mΩ
		V _{GS} =-2.5V,I _{DS} =-7.7A	ı	15	20	
	NOTE#	V _{GS} =-1.8V,I _{DS} =-3A	ı	22	32	
Diode Characteristics						
Diode Forward Voltage	V _{SD} NOTE4	I _{SD} =-1A,V _{GS} =0V	ı	-0.7	-1	V
Reverse Recovery Time	t _{rr} NOTE5	I _{SD} =-12.2A,	ı	18	-	ns
Reverse Recovery Charge	Q _{rr} NOTE5	dl _{SD} /dt=100A/μs	1	9	-	nC
Dynamic Characteristics NOTE5						
Gate Resistance	Rg	Vgs=0V,Vps=0V,F=1MHz	1	3	-	Ω
Input Capacitance	Ciss	V _{GS} =0V,	1	1790	-	
Output Capacitance	Coss	V _{DS} =-10V,	1	388	-	рF
Reverse Transfer Capacitance	Crss	Frequency=1.0MHz	1	310	-	
Turn-on Delay Time	t _{D(ON)}	V = 40V D =400	1	10	-	
Turn-on Rise Time	t _R	V_{DD} =-10V, R_L =10 Ω I_{DS} =-1A, V_{GEN} =-10V, R_G =6 Ω	ı	14	-	ns
Turn-off Delay Time	t _{D(OFF)}		1	80	-	
Turn-off Fall Time	t⊧		-	65	-	
Gate Charge Characteristics NOTE3						
Total Gate Charge	Q _G	V _{DS} =-10V, V _{GS} =-4.5V, I _{DS} =-12.2A	ı	22	-	nC
Gate-Source Charge	Q _{GS}		-	1.2	-	
Gate-Drain Charge	Q_{GD}		ı	10.5	-	

NOTE4: Pulse test; pulse width \leq 300µs, duty cycle \leq 2%.

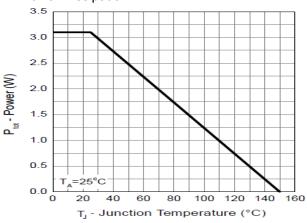
NOTE5: Guaranteed by design, not subject to production testing.

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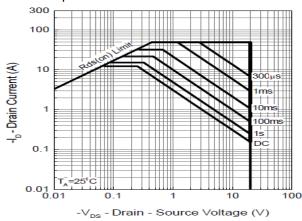


TYPICAL CHARACTERISTICS

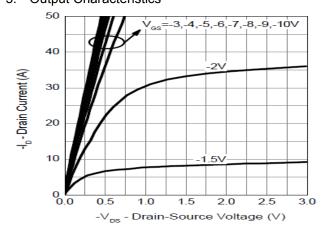
1. Power Dissipation



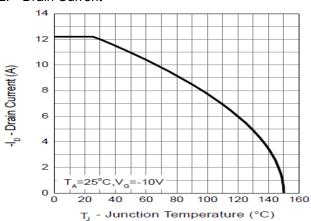
3. Safe Operation Area



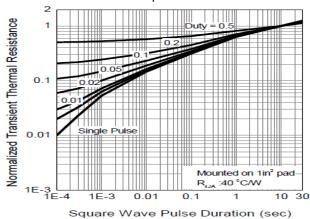
5. Output Characteristics



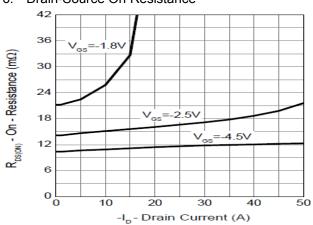
2. Drain Current



4. Thermal Transient Impedance



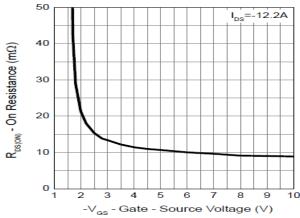
6. Drain-Source On Resistance



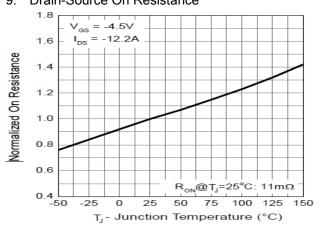
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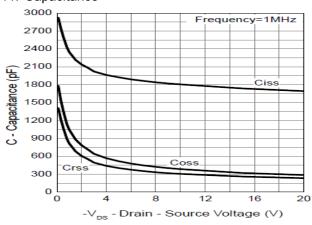
7. Gate-Source On Resistance



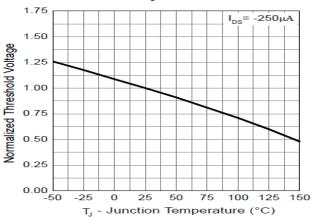
9. Drain-Source On Resistance



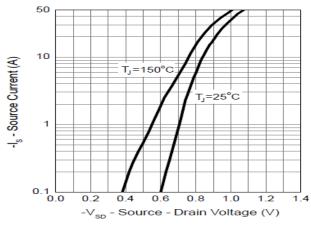
11. Capacitance



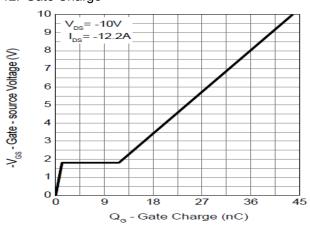
8. Gate Threshold Voltage



10. Source-Drain Diode Forward



12. Gate Charge

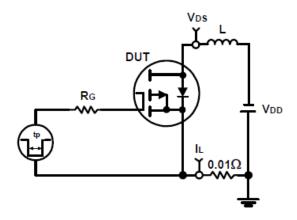


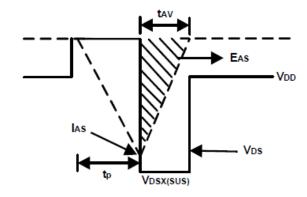
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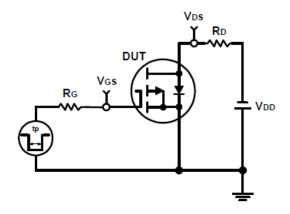
DETAILED INFORMATION

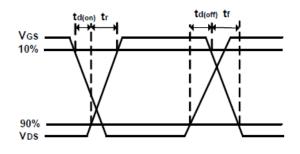
Avalanche Test Circuit and Waveforms





Switching Time Test Circuit and Waveforms

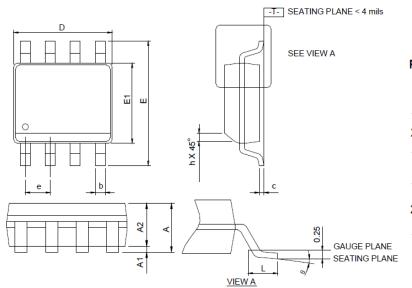




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PACKAGE INFORMATION

Dimension in SOP8 (Unit: mm)



1.27 2.2 5.74 2.87 0.635 UNIT: mm

Symbol	Min	Max	
А	-	1.750	
A1	0.100	0.250	
A2	1.250	-	
b	0.310	0.510	
С	0.170	0.250	
D	4.800	5.000	
E	5.800	6.200	
E1	3.800	4.000	
е	1.270(BSC)		
h	0.250	0.500	
L	0.400	1.270	
θ	0°	8°	

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